ST has two kinds of manufacturing sites: Front-end and Back-end

The Front-end sites produce transistors and integrated circuits on silicon ‘wafers’ through a series of complex processes that enable the transistors in the silicon chip to process electronic information or control the flow of electrical power. The thin slices of silicon range from 5 to 12 inches in diameter, with more advanced technology being required to produce the larger diameters.

Back-end sites perform assembly, packaging and testing functions. The individual silicon ‘die’ or rectangles are cut from the wafers and the die are then sealed with wire connections into the ‘package’ or box that connects the chips to an electronic device. The chips are then tested to ensure quality and proper performance.

For more information on ST’s company profile, see www.st.com